

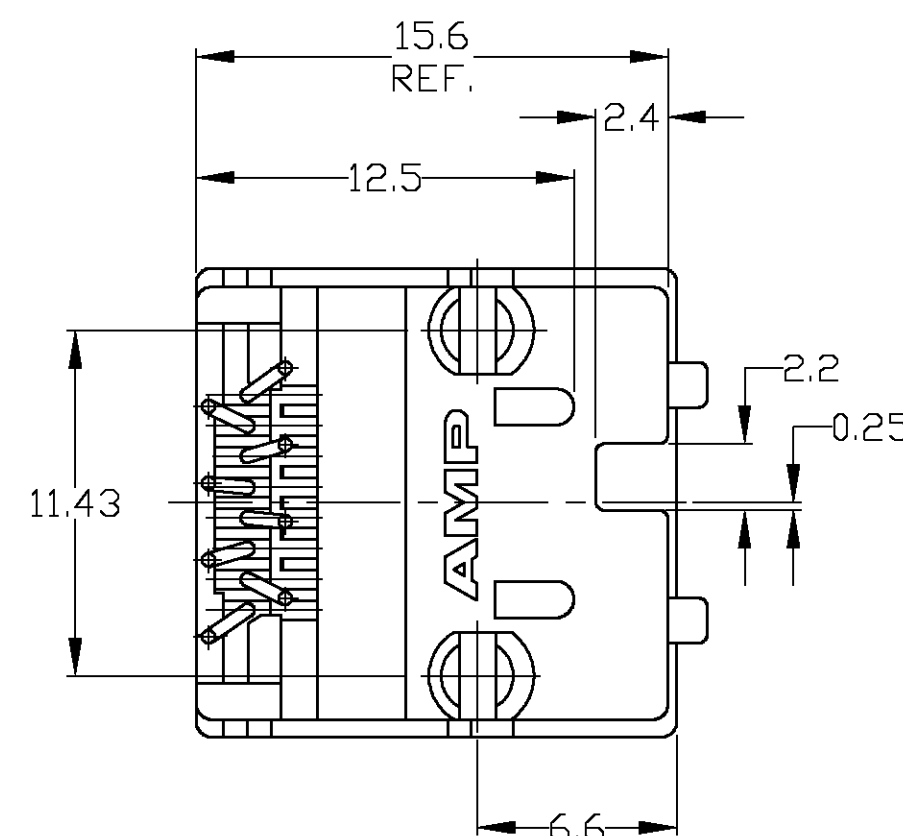
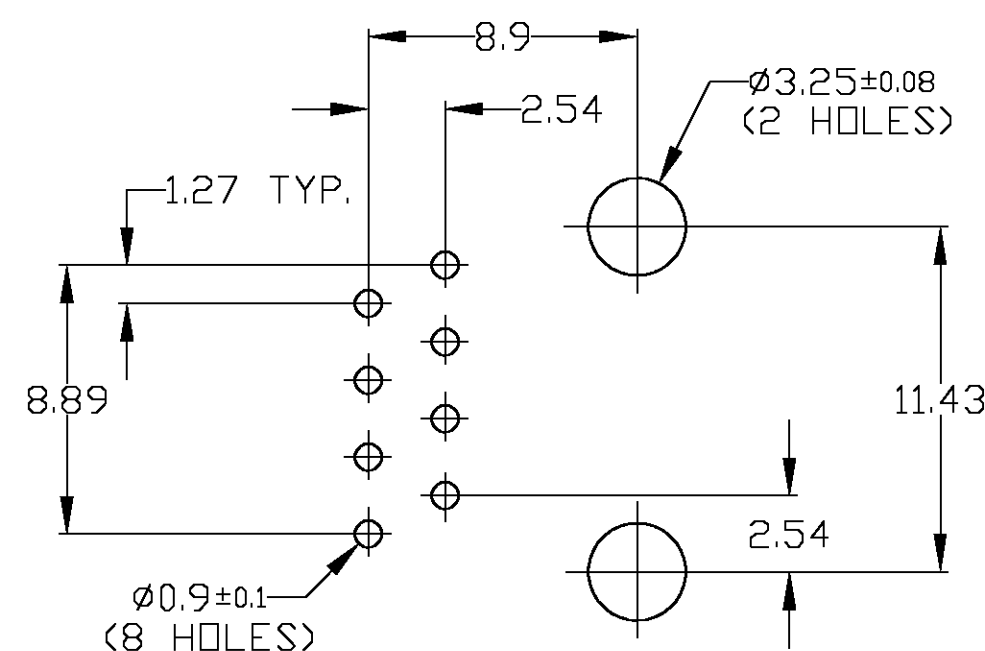
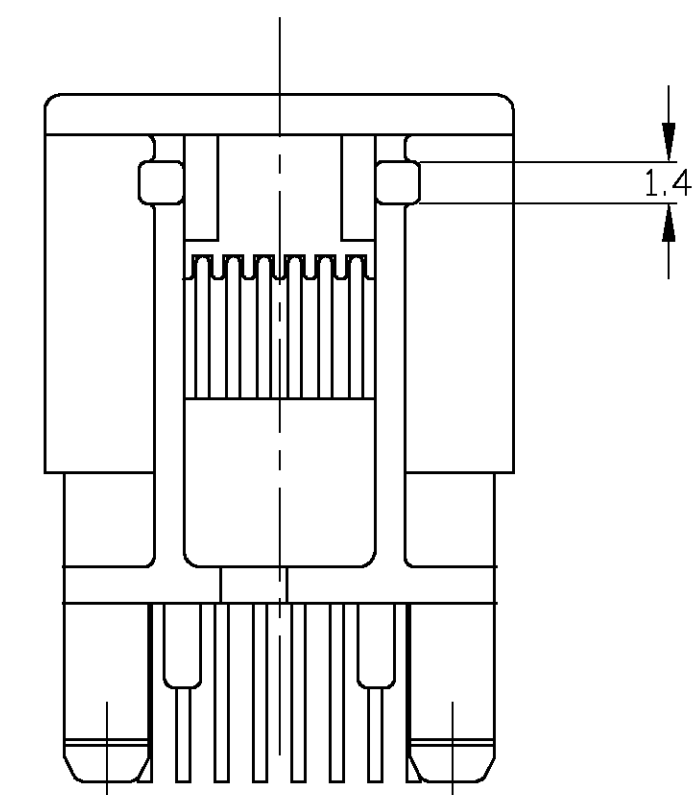
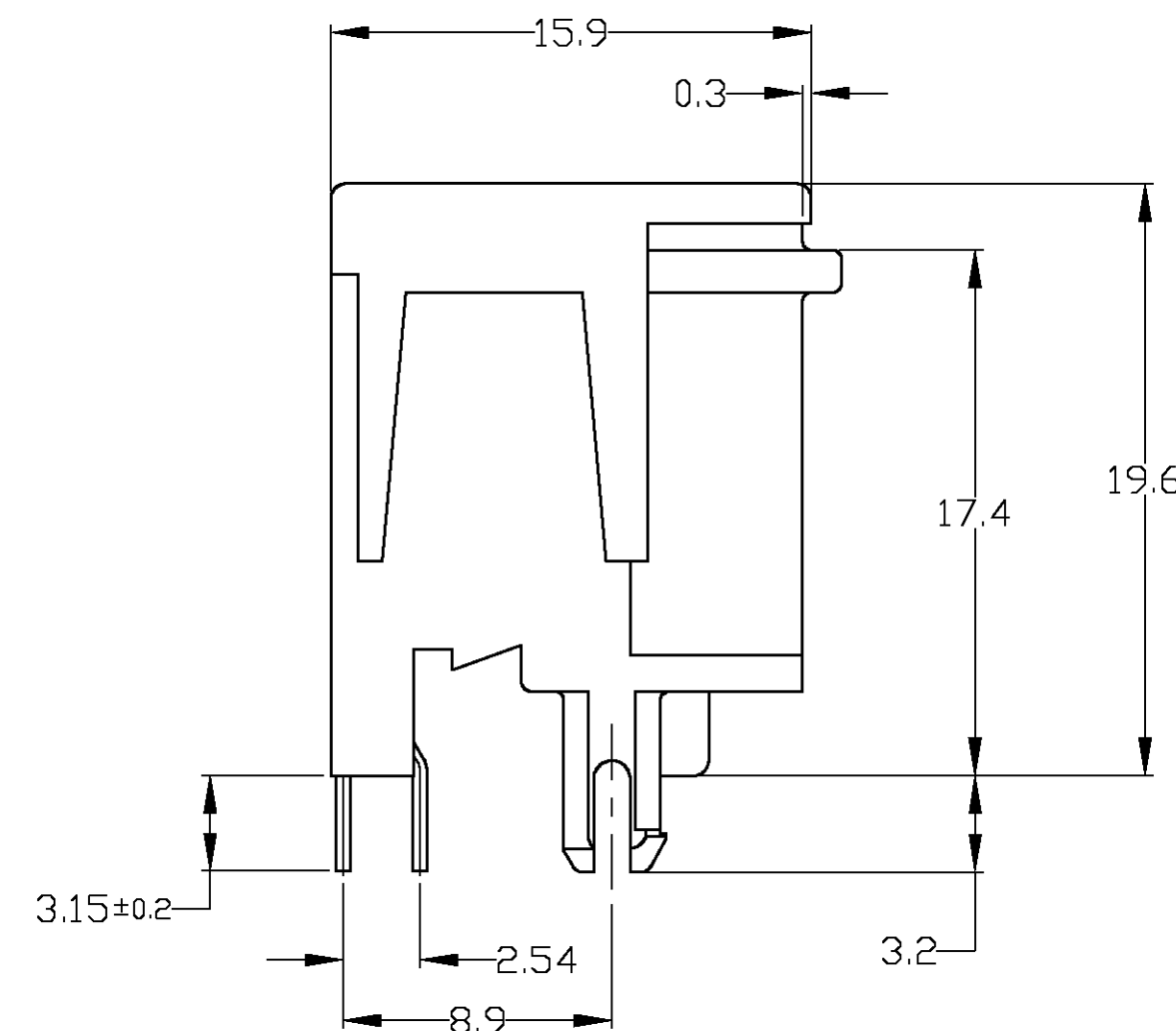
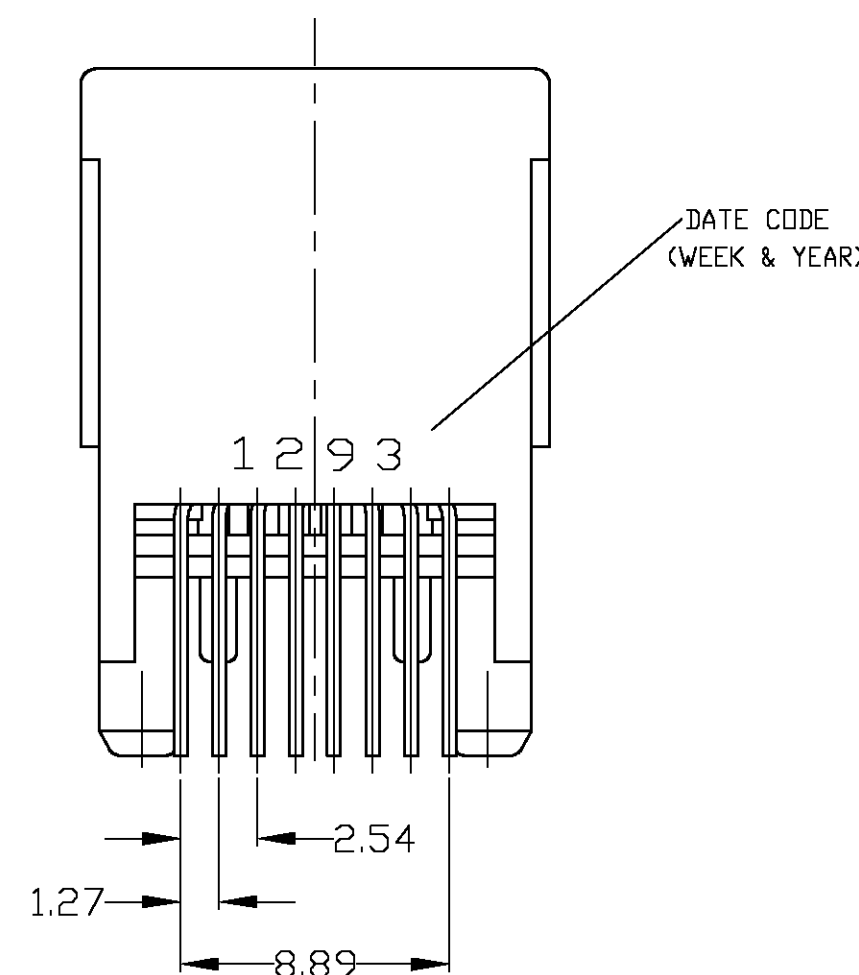
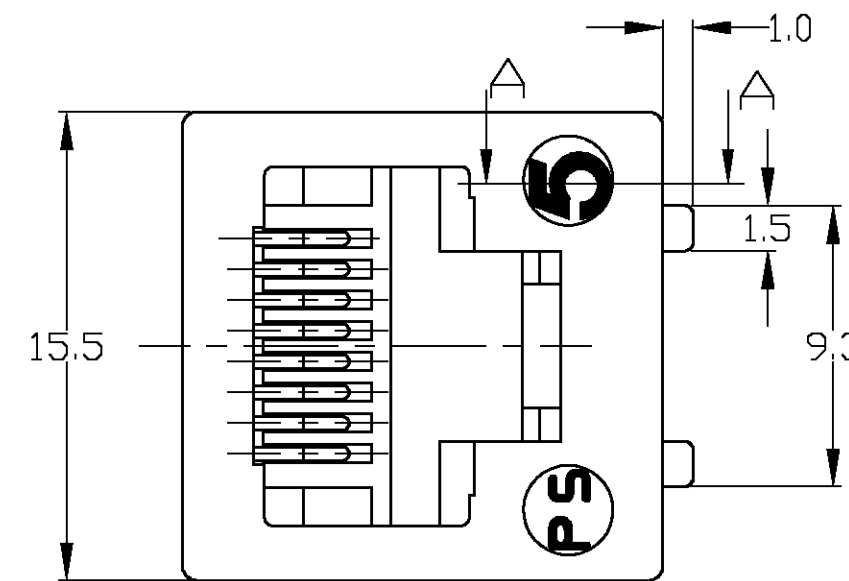
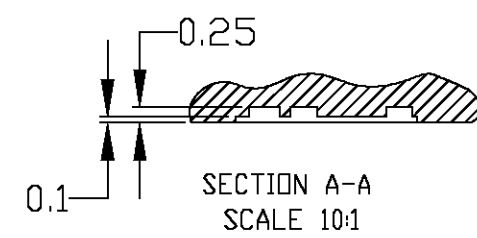
DO NOT SCALE
DIMENSIONS IN mm

METRIC

THIRD ANGLE
PROJECTION

NOTES:

- 1 TOLERANCES UNLESS OTHERWISE SPECIFIED: $\pm 0,15$.
- 2 CONTACTS:
1,27 μm MIN. GOLD, SELECTIVE IN CONTACT AREA, OVER 1,27 μm MIN. NICKEL.
2,0 μm MIN. TIN-LEAD OVER 1,27 μm MIN. NICKEL ON SOLDER TINES.
- 3 HOUSING:
PBT, COLOR BLACK, UL 94V-0
CONTACTS:
PHOSPHOR BRONZE.
- 4 FOR APPLICATION INFORMATION SEE AMP SPEC. 114-19019.
- 5 FOR PERFORMANCE REQUIREMENTS SEE AMP SPEC. 108-19064.
- 6 PACKAGING: BULK PACKAGED.
TRUE POSITIONING OF THE SOLDER TINES,
MAY BE AFFECTED BY BULK PACKAGING.



PRINTED CIRCUIT BOARD LAYOUT

[VIEW SHOWN IS CIRCUIT (NONCOMPONENT) SIDE OF BOARD.]

PRINTED CIRCUIT BOARD THICKNESS: 1,6 mm NOMINAL.

TOLERANCES UNLESS OTHERWISE SPECIFIED: $\pm 0,05$.

8 POS. / 8 CONT.		FINISH		MATERIAL		338360-1
DESCRIPTION		FINISH		MATERIAL		P/N
				CUSTOMER DRAWING		FOR REFERENCE ONLY WILL NOT BE UPDATED
				© COPYRIGHT 19 BY AMP HOLLAND B.V.		
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				COVERED BY U.S. AND FOREIGN AND/OR PATENTS PENDING.		
				THIS DRAWING IS UNPUBLISHED		
				RELEASED FOR PUBLICATION		
B	SR10-0084-02	KV	06 FEB 02	tyco Electronics		Tyco Electronics Corporation Oostkamp - BELGIUM
A	EH-1142-97	EVE	W.B. 18 NOV 97	NAME MODULAR JACK, 8 POS., TOP ENTRY		
O	EH-0870-97	EVE	W.B. 12 AUG 97	HIGH PROFILE, WITH SPECIAL PANEL STOPS		
LTR.	REVISION RECORD	DR.	CHK.	DATE	FOR PRINTED CIRCUIT BOARD	
DR.: E.v.EJK		CHK.: W.BRUMMANS		APP.: R.SMEETS		DWG.No.
DATE: 12 AUG 97		DATE:		DATE:		C-338360
				REV.LTR.		SHEET
				B		1 OF 1
						A2

Mouser Electronics

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[TE Connectivity:](#)

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